

202220-00928001

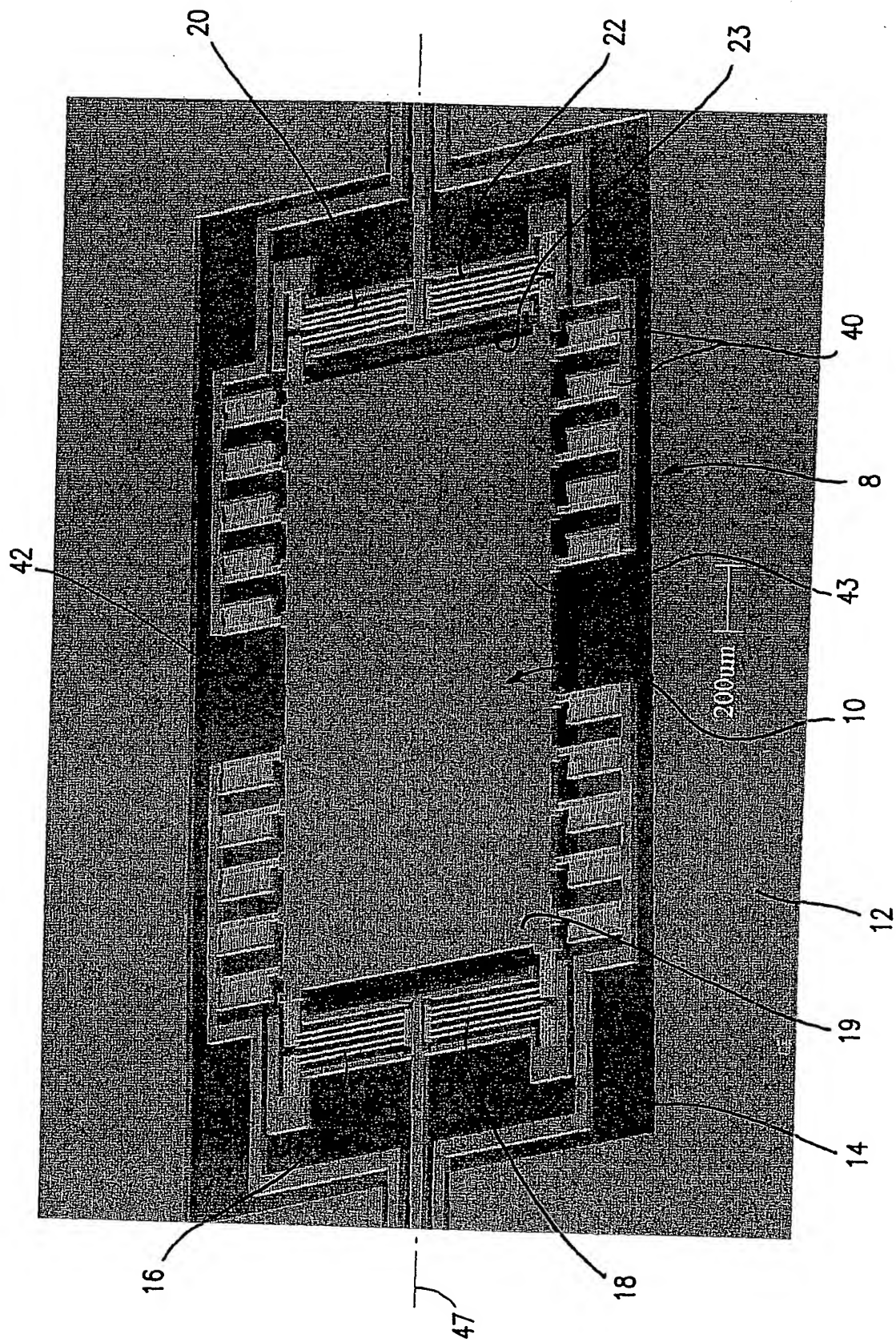
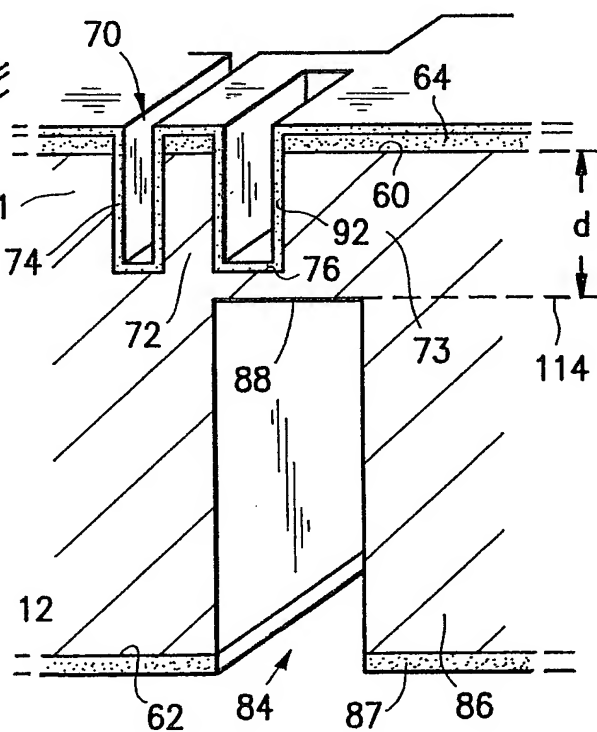
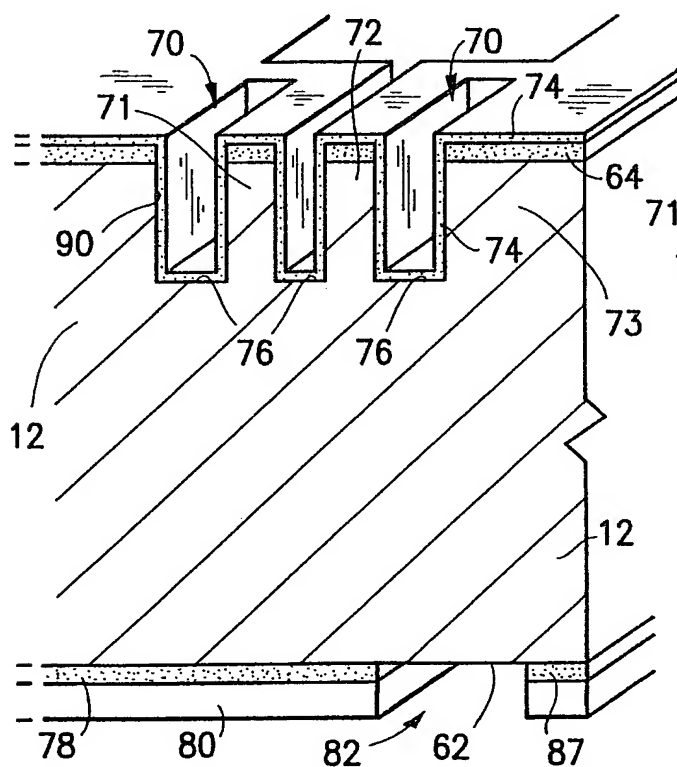
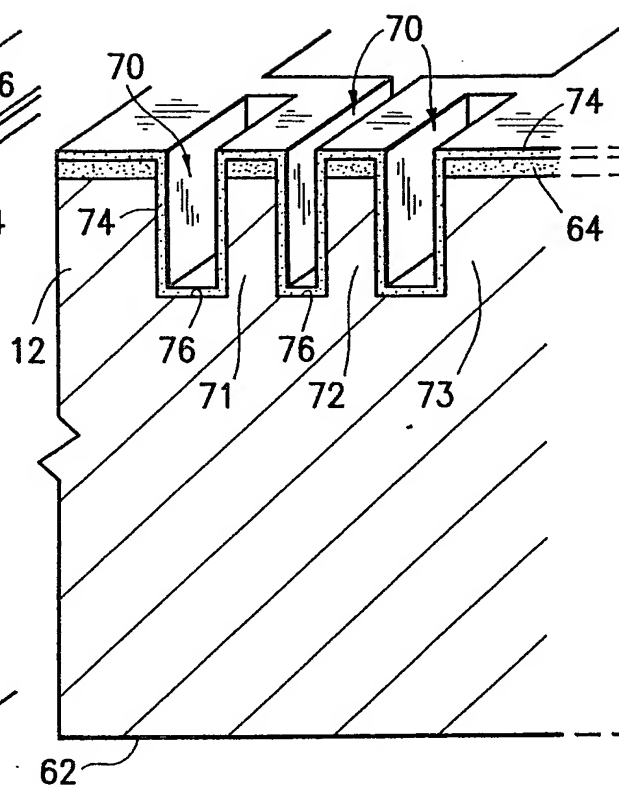


FIG. 1

FIG. 2

A cross-sectional view of a multi-layered structure. The top layer, labeled 60, consists of a series of rectangular blocks separated by recessed channels. The top surface of these blocks is textured, indicated by horizontal lines. A curved arrow labeled 68 points to the top surface of one of the blocks. The blocks are separated by recessed channels, with one channel labeled 66. Below the top layer is a substrate, labeled 62, which is filled with diagonal hatching. The interface between the top layer and the substrate is labeled 64. The overall structure is labeled 12.



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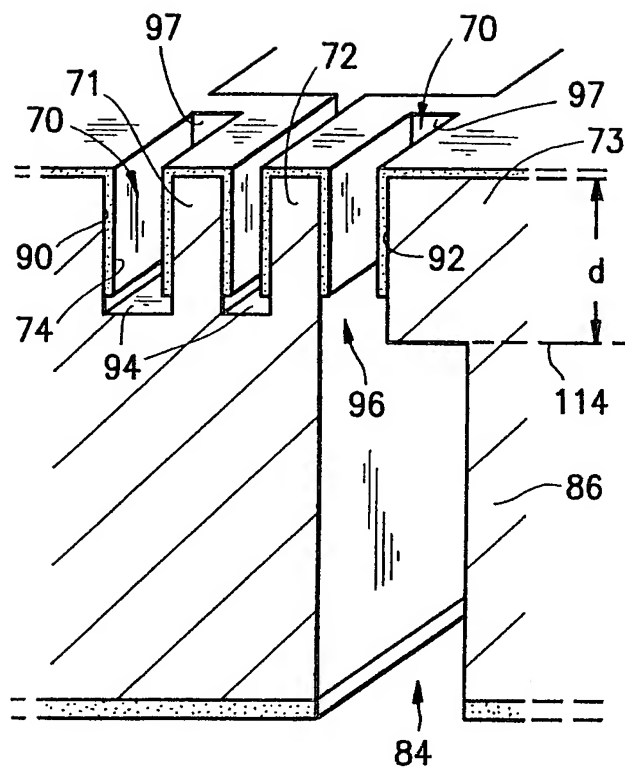


FIG. 7

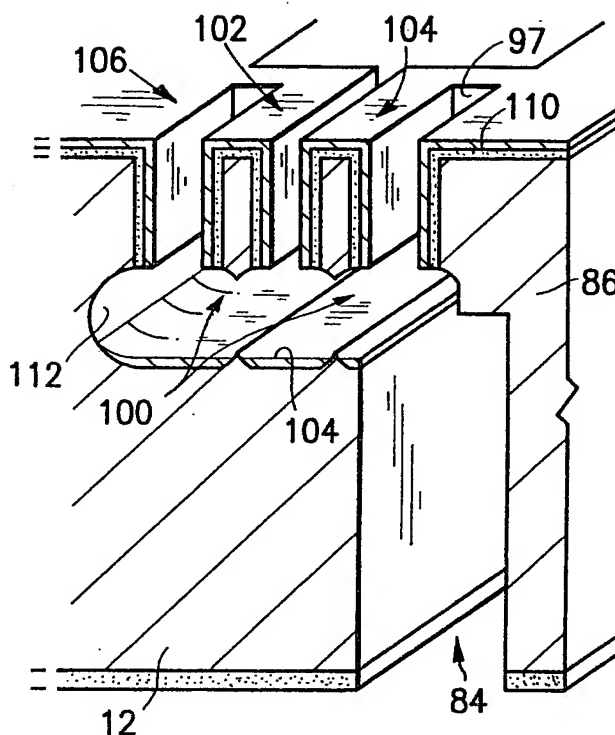


FIG. 8

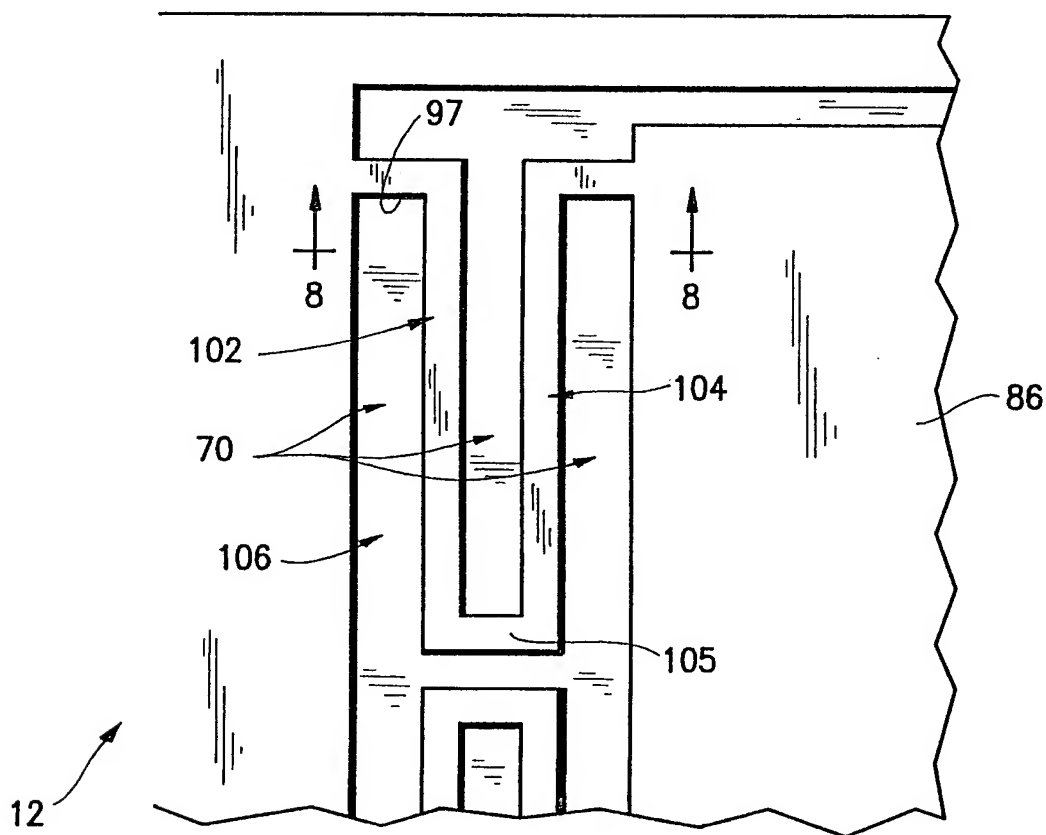


FIG. 9

FIG. 10

FIG. 11 is a perspective view of a semiconductor device. It shows a central array of elements (152) surrounded by various interconnects and pads. Labels include 162, 152, 144, 154, 160, 130, 120, 164, 150, 148, 122, and 124.

FIG. 11



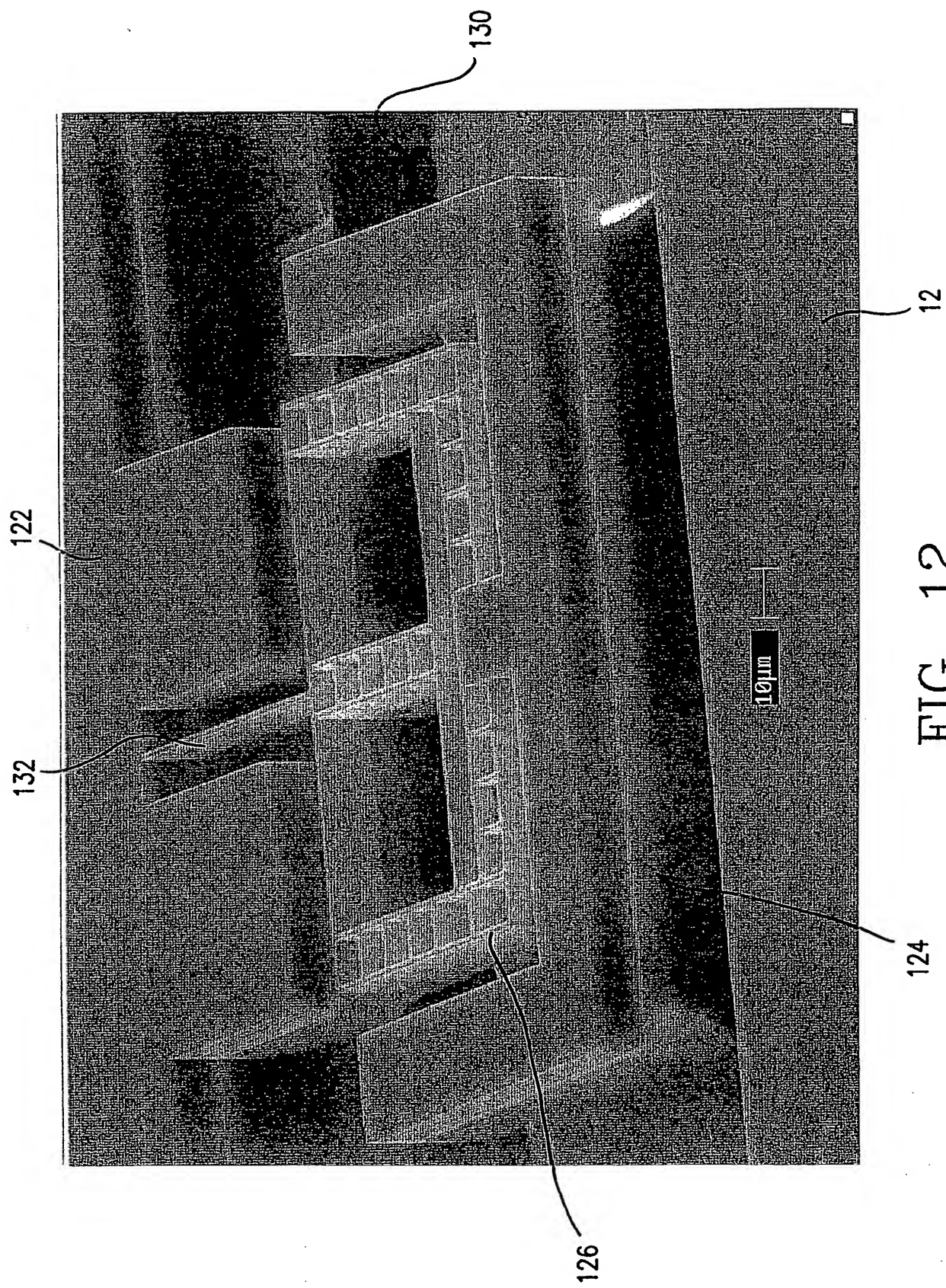


FIG. 12

FIG. 13

FIG. 13